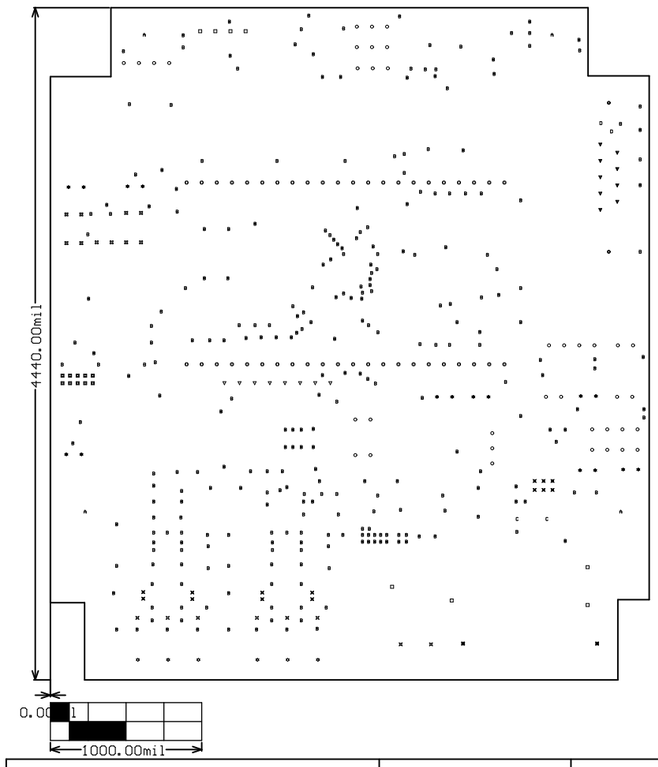
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✡	6	137.80mil (3,500mm)	NPTH	Round	Top Layer - Bottom Layer	
A	4	196.85mil (5.000mm)	NPTH	Round	Top Layer - Bottom Layer	
✖	14	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
B	294	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◘	10	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
D	2	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
C	2	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
✪	44	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	10	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+/-3.94mil
▽	8	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
○	38	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▼	9	41.00mil (1.041mm)	PTH	Round	Top Layer - Bottom Layer	+/-5.00mil
✖	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
✱	16	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	8	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
●	2	121.00mil (3.073mm)	PTH	Round	Top Layer - Bottom Layer	+/-2.00mil
	477 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 0.5 mm
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☒ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☐ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-VO REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-010036	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: TIDA-010036		
PLOT NAME = Fabrication Drawing	GENERATED : 4/12/2019 11:05:13 AM		TEXAS INSTRUMENTS